4-Bit Bus Switch

The ON Semiconductor 74FST3125 is a quad, high performance switch. The device is CMOS TTL compatible when operating between 4 and 5.5 Volts. The device exhibits extremely low R_{ON} and adds nearly zero propagation delay. The device adds no noise or ground bounce to the system.

The device consists of four independent 1-bit switches with separate Output/Enable (\overline{OE}) pins. Port A is connected to Port B when \overline{OE} is low. If \overline{OE} is high, the switch is high Z.

Features

- $R_{ON} < 4 \Omega$ Typical
- Less Than 0.25 ns-Max Delay Through Switch
- Nearly Zero Standby Current
- No Circuit Bounce
- Control Inputs are TTL/CMOS Compatible
- Pin-For-Pin Compatible With QS3125, FST3125, CBT3125
- All Popular Packages: QSOP-16, TSSOP-14, SOIC-14
- All Devices in Package TSSOP are Inherently Pb-Free*

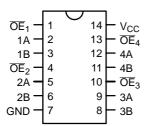
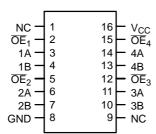
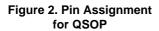


Figure 1. Pin Assignment for SOIC and TSSOP

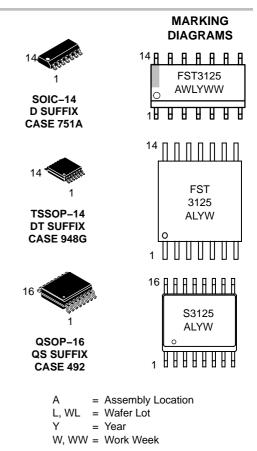






ON Semiconductor[®]

http://onsemi.com



PIN NAMES

Pin	Description				
$\overline{OE}_1, \overline{OE}_2, \overline{OE}_3, \overline{OE}_4$	Bus Switch Enables				
1A, 2A, 3A, 4A	Bus A				
1B, 2B, 3B, 4B	Bus B				
NC	Not Connected				

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



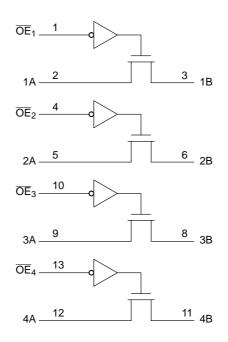


Figure 3. Logic Diagram

TRUTH TABLE

Inputs	Outputs
ŌĒ	А, В
L	A = B
Н	Z

ORDERING INFORMATION

Device Order Number	Package	Shipping [†]
74FST3125D	SOIC-14	55 Units / Rail
74FST3125DR2	SOIC-14	2500 Units / Tape & Reel
74FST3125DT	TSSOP* (Pb–Free)	96 Units / Rail
74FST3125DTR2	TSSOP* (Pb–Free)	2500 Units / Tape & Reel
74FST3125QS	QSOP-16	96 Units / Rail
74FST3125QSR	QSOP-16	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

MAXIMUM RATINGS

Symbol	P	arameter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		-0.5 to +7.0	V
Vo	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	$V_{I} < GND$	-50	mA
I _{OK}	DC Output Diode Current	$V_{O} < GND$	-50	mA
Ι _Ο	DC Output Sink Current		128	mA
I _{CC}	DC Supply Current per Supply Pin		±100	mA
I _{GND}	DC Ground Current per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case f	or 10 Seconds	260	°C
ТJ	Junction Temperature Under Bias		+ 150	°C
θ_{JA}	Thermal Resistance (Note 1)	SOIC TSSOP QSOP	125 170 200	°C/W
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >200	V
I _{Latchup}	Latchup Performance	Above V _{CC} and Below GND at 85 $^{\circ}$ C (Note 4)	±500	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

Tested to EIA/JESD22-A114-A.
Tested to EIA/JESD22-A115-A.
Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Par	Parameter			Unit
V _{CC}	Supply Voltage	Operating, Data Retention Only	4.0	5.5	V
VI	Input Voltage	(Note)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	V _{CC}	V
T _A	Operating Free–Air Temperature		- 40	+ 85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	Switch Control Input Switch I/O	0 0	5 DC	ns/V

5. Unused control inputs may not be left open. All control inputs must be tied to a high- or low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	T _A = -	40°C to	+85°C	
Symbol	Parameter	Conditions	(V)	Min	Тур*	Max	Unit
V _{IK}	Clamp Diode Resistance	$I_{IN} = -18 \text{mA}$	4.5			-1.2	V
V _{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V _{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
lı	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μΑ
I _{OZ}	OFF-STATE Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R _{ON}	Switch On Resistance (Note 6)	$V_{IN} = 0 V$, $I_{IN} = 64 mA$	4.5		4	7	Ω
		$V_{IN} = 0 V, I_{IN} = 30 mA$	4.5		4	7	
		$V_{IN} = 2.4 \text{ V}, I_{IN} = 15 \text{ mA}$	4.5		8	15	
		$V_{IN} = 2.4 \text{ V}, I_{IN} = 15 \text{ mA}$	4.0		11	20	
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	5.5			3	μΑ
ΔI_{CC}	Increase In I _{CC} per Input	One input at 3.4 V, Other inputs at $V_{\mbox{\scriptsize CC}}$ or GND	5.5			2.5	mA

*Typical values are at $V_{CC} = 5.0$ V and $T_A = 25^{\circ}C$. 6. Measured by the voltage drop between A and B pins at the indicated current through the switch.

AC ELECTRICAL CHARACTERISTICS

				$Limits$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$				
				V _{CC} = 4.5	-	0 + 85°C = V _{CC}		
Symbol	Parameter	Conditions	Figures	Min	Max	Min	Max	Unit
t _{PHL} , t _{PLH}	Prop Delay Bus to Bus (Note 7)	V _I = OPEN	4 and 5		0.25		0.25	ns
t _{PZH} , t _{PZL}	Output Enable Time	$V_I = 7 V$ for t_{PZL} $V_I = OPEN$ for t_{PZH}	4 and 5	1.0	5.0		5.5	ns
t _{PHZ} , t _{PLZ}	Output Disable Time	$V_I = 7 V \text{ for } t_{PLZ}$ $V_I = OPEN \text{ for } t_{PHZ}$	4 and 5	1.5	5.3		5.6	ns

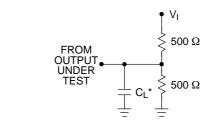
This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

CAPACITANCE (Note 8)

Symbol	Parameter	Conditions	Тур	Мах	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 5.0 V	3		pF
C _{I/O}	Input/Output Capacitance	$V_{CC}, \overline{OE} = 5.0 V$	5		pF

8. $T_A = +25^{\circ}C$, f = 1 MHz, Capacitance is characterized but not tested.

AC Loading and Waveforms

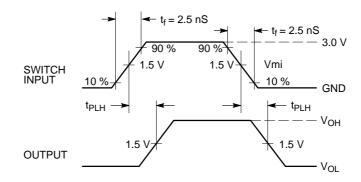


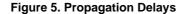
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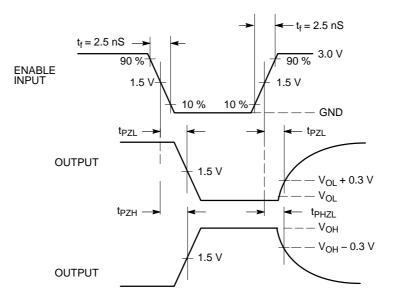
1. Input driven by 50 Ω source terminated in 50 $\Omega.$

2. CL includes load and stray capacitance. $^{\ast}\text{C}_{\text{L}}$ = 50 pF







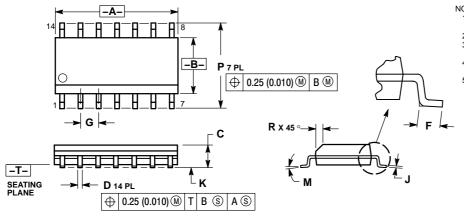






PACKAGE DIMENSIONS



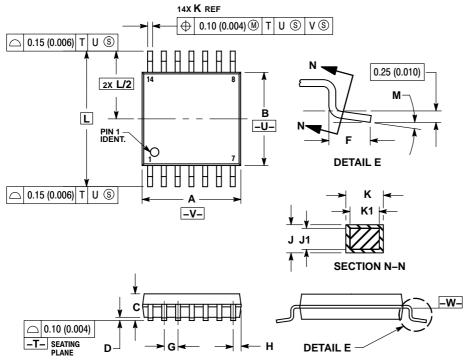


NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
ĸ	0.10	0.25	0.004	0.009
М	0 °	7 °	0 °	7 °
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE O**



NOTES:

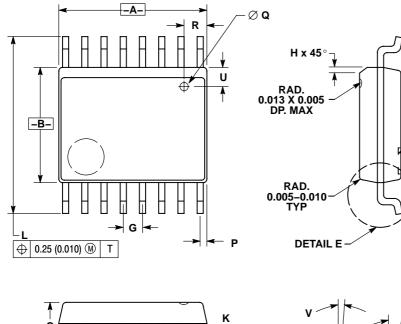
- IOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- PEH SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- MATERIAL CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
ſ	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
Μ	0 °	8°	0°	8 °



PACKAGE DIMENSIONS

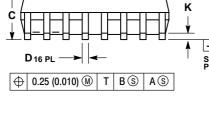


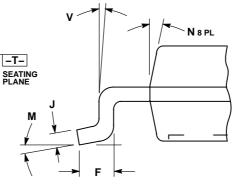


MOLD PIN MARK

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. THE BOTTOM PACKAGE SHALL BE BIGGER THAN THE TOP PACKAGE BY 4 MILS (NOTE: LEAD SIDE ONLY). BOTTOM PACKAGE DIMENSION SHALL FOLLOW THE DIMENSION STATED IN THIS DRAWING. 4. PLASTIC DIMENSIONS BODES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 6 MILS PER SIDE. 5. BOTTOM EJECTOR PIN WILL INCLUDE THE
- 5. BOTTOM EJECTOR PIN WILL INCLUDE THE COUNTRY OF ORIGIN (COO) AND MOLD CAVITY I.D.

	INC	HES	MILLIM	ETERS
DIM	MAX	MIN	MAX MIN	
Α	0.189	0.196	4.80	4.98
В	0.150	0.157	3.81	3.99
С	0.061	0.068	1.55	1.73
D	0.008	0.012	0.20	0.31
F	0.016	0.035	0.41	0.89
G	0.025	BSC	0.64	BSC
н	0.008	0.018	0.20	0.46
J	0.0098	0.0075	0.249	0.191
Κ	0.004	0.010	0.10	0.25
L	0.230	0.244	5.84	6.20
М	0 °	8 °	0 °	8 °
Ν	0 °	7°	0 °	7°
Р	0.007	0.011	0.18	0.28
Q	0.020	20 DIA 0.51 DIA		DIA
R	0.025	0.035	0.64	0.89
U	0.025	0.035	0.64	0.89
٧	0 °	8°	0 °	8°





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